

PRESS RELEASE

For release Wednesday, March 8, 2017

Contact:

Sally Bixby, Senior Events Director
The ConFab 2017, Extension Media
+1 (503) 705 8651
sbixby@extensionmedia.com

The ConFab 2017 Announces Leading Semiconductor Industry Keynotes

The ConFab, Premier Semiconductor Manufacturing Conference for Executives, Announces Keynotes and Influential Industry Speakers in May 2017 Program

San Francisco, CA – [The ConFab](#) - an exclusive conference and networking event for semiconductor manufacturing and design executives from leading device makers, OEMs, OSATs, fabs, suppliers and fabless/design companies - announces Keynotes in the May 14-17 event being held at the Hotel del Coronado in San Diego.

The ConFab 2017 is excited to welcome these distinguished Keynote speakers: Hans Stork, Senior Vice President and Chief Technical Officer at ON Semiconductor; Mohan Trivedi, Distinguished Professor of Electrical and Computer Engineering and founding director of the Computer Vision and Robotics Research Laboratory, as well as the Laboratory for Intelligent and Safe Automobiles at the University of California San Diego; Dr. Alissa Fitzgerald, Founder and Managing Member of A.M. Fitzgerald & Associates, and Bill McClean, President of IC Insights.

“The five hottest areas for semiconductor growth in the coming years are the Internet of Things (IoT), automotive, 5G, virtual reality/augmented reality (VR/AR), and artificial intelligence (AI). The ConFab 2017 program will take a close look at the challenges of these applications in the semiconductor industry, not just on the microprocessor and memory side, but on the MEMS, sensor, display, power and analog side. Many new innovations in packaging will also addressed,” said Pete Singer, Conference Chair of The ConFab and Editor-in-Chief of *Solid State Technology*.

In addition to our great Keynotes, the 2017 [Agenda](#) brings together sessions on heterogeneous integration and advanced packaging, starting with a talk from Islam Salama, Director with Intel, followed by Bill Chen, ASE Fellow, and Jan Vardaman, President of TechSearch. Siemens will speak on Smart Manufacturing, which will encompass the Industrial Internet of Things (IIoT). A panel discussion on Advanced Packaging will be moderated by Vinayak Pandey, Vice President of STATS ChipPAC with additional sessions that will focus on MEMS and sensors. Speakers include Kevin Shaw, CTO and Founder of Algorithmic Intuition and J.C. Eloy, President and CEO of Yole Développement. Another panel will look into the coming opportunities and changes in a range of diverse markets, including MEMS and Sensors, power electronics, biomedical, LEDs, displays and more. Those panelists include Valerie Marty of Connected Micro, Laura Rothman Mauer of Veeco, David Butler of SPTS and Mike Rosa of Applied Materials. Jason Marsh of NextFlex will provide an update on flexible electronics on Wednesday.

The ConFab is a high-level conference for decision-makers and influencers to connect, innovate and collaborate in multiple sessions, one-on-one private business meetings, and other networking activities. For more information, visit www.theconfab.com.

About The ConFab

The ConFab is the premier semiconductor manufacturing conference and networking event bringing over 200 notable industry leaders together. The ConFab is owned and produced by Extension Media and hosted by Pete

Singer, *Solid State Technology*'s Editor-in-Chief, and Conference Chair. To inquire about participating - if you represent an equipment, material or service supplier, contact Kerry Hoffman, Director of Sales, at khoffman@extensionmedia.com. To inquire about attending, contact Sally Bixby, Sr. Events Director at sbixby@extensionmedia.com

About Extension Media

[Extension Media](#) is a privately held company operating more than 50 B2B magazines, engineers' guides, newsletters, websites and conferences that focus on high-tech industry platforms and emerging technologies such as: chip design, semiconductor and electronics manufacturing, embedded systems, software, architectures and industry standards. Extension Media also produces industry leading events including The ConFab, the Internet of Things Developers Conference ([IoT DevCon 2017](#)) and the new Machine Learning Developers Conference ([ML DevCon 2017](#)), and publishes *Embedded Systems Engineering*, *EECatalog.com*, *Embedded Intel® Solutions*, *EmbeddedIntel.com*, *Chip Design*, *ChipDesignMag.com*, *Solid State Technology* and *Solid-State.com*.

###